

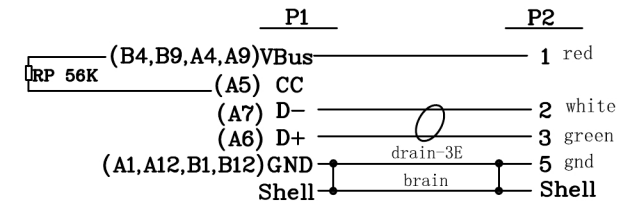
1. test conditions:

- 1.100% of short circuit, open circuit test & dislocation.
2. Insulation impedance: 10M ohm (MIN) DC 300V.
3. Conduction impedance: 2 ohm (MAX).
4. Withstand voltage test: DC 300V/10ms

2. processing instructions:

1. C Type end was peeling 8-10 mm, outside with thread gauge sequence will conductor LiRu fixture groove (ground to put in GND PIN), woven take 2 ~ 3 shares of twist in the Shell welding Pad, pay attention to the tin point should not be too large.
2. Micro USB BF side 3 e ground of twisting the welding in GND Pad, weaving take 2 ~ 3 shares of twisting the welding welding on the steel casing.
3. The P1 end after good conductor welding the PCB must be UV glue, UV glue dozen thin as far as possible,

Pin Assignment:



⑩	A0040411-00002	Low pressure molding compound, transparent color, hardness, 40 ~ 48 d	1	g
⑨	A0020100-00173	USB TYPE C~The tin plating nickel	1	PCS
⑧	A0020100-00172	USB TYPE C~On the tin plating nickel	1	PCS
⑦	A10-R075552	Heat shrinkable casing~ ϕ 1.0mm~black	0.016	M
⑥	A5-R047001	45P BLACK PVC ROHS	16	g
⑤	A5-R047011	transparent PE ROHS LDPE	4	g
④	A6-R107406-1	Micro USB B TYPE 5PIN F HOOD~ABS~BLACK	1	PCS
③	A2-R028553	Micro USB B TYPE 5PIN F SHELL PLATED:NICKEL CONTACT:G/F	1	PCS
②		TYPE C-Type Connector With empty PCB+SMT	1	PCS
①	A4-R005013	NO-UL 30AWG (19/0.06TC)*2C+24AWG (26/0.1TC+250Dnylon)+3E (19/0.05TC+250Dnylon)+AB (16/9/0.06TC 95%铜编) OD:3.0MM 黑色PVC 无印字	0.15	M
NO	CELINK P/N	DESCRIPTION	QTY	

REV.	ECN		DESCRIPTION		DATE	NAME	
	TOLERANCE INCHES M/M			TITLE: USB2.0 CM TO Micro BF L=150MM			
	.X	.015	.30				
	.XX	.010	.10				
	.XXX	.005	.05				
DRAWN BY	zhouwenlong		CUSTOMER :		CPC		
			CUSTOMER NO.:		PSG91482		
CHECK BY			SCALE	NONE		DRAWING NO.:	REV. A01
			UNIT	MM			
APPD BY			DATE	2017.05.03		C06026-00265	1/2